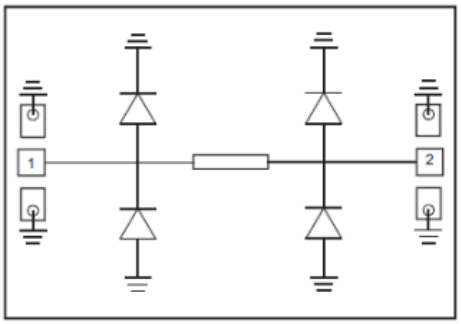
Features

- Frequency:15-40GHz
- Insertion Loss: 0.9dB(typ.)
- Limit Power:18dBm
- Tolerance Power:30dBm(CW)
- Input/Output: 50Ω
- Die Size: 1.64x0.72x 0.1 mm

Functional Block Diagram



Typical Applications

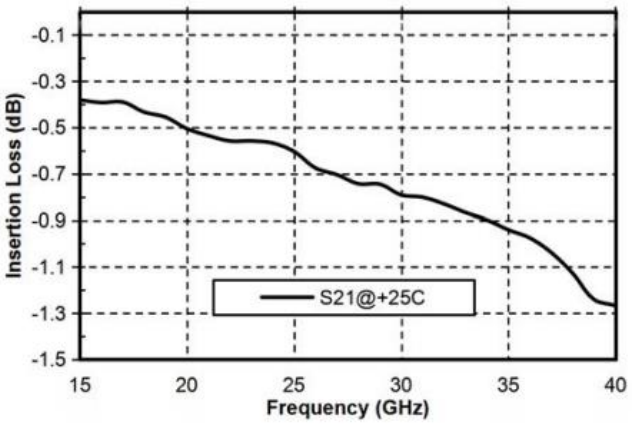
- Test Instrumentation
- Microwave Radio & VSAT
- Military & Space
- Telecom Infrastructure
- Fiber Optics

Electrical Specifications

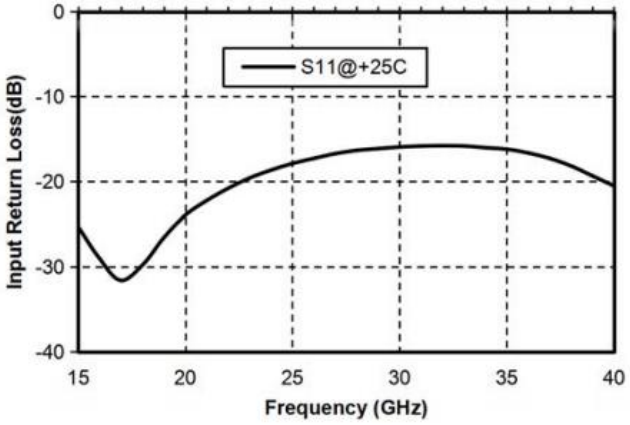
TA = +25ºC

Parameters	Min.	Typ.	Max.	Units
Frequency		**15-40**		**GHz**
Insertion Loss	**-**	**0.9**	**1.3**	**dB**
Input Return Loss	**15**	**17**	**-**	**dB**
Output Return Loss	**16**	**17**	**-**	**dB**
Limit Power	**-**	**18**	**-**	**dBm**
Tolerance Power		**30**		**dBm**

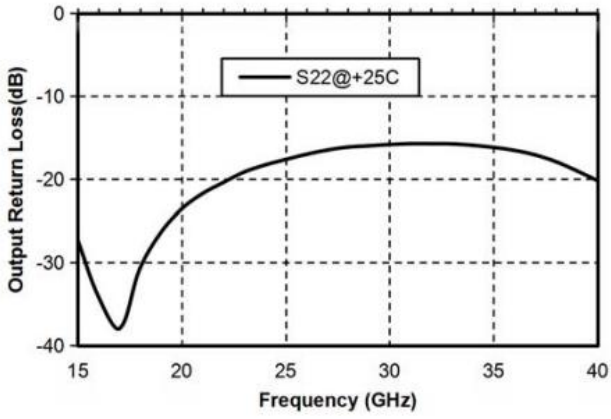
Insertion Loss Vs. Frequency



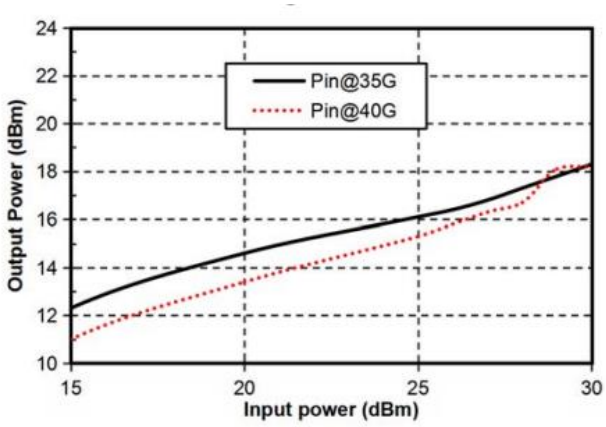
Input Return Loss Vs. Frequency



Output Return Loss Vs. Frequency



Limit Power @35G 40G



Outline Drawing:

All Dimensions in um, tolerance range ±50um

Pad Description

PAD	Function	Description
1	RF IN	RF signal input, A DC blocking capacitor has been integrated at the input of the chip
2	RF OUTPUT	RF signal output, A DC blocking capacitor has been integrated at the output of the chip
Die Bottom	GND	Die bottom must be connected to RF/DC ground.

Assembly Drawing

Notes:

1. Die thickness: 100um
2. Typical bond pad is 100*100 μm²
3. Bond pad metalization: Gold
4. Backside metalization: Gold
5. Backside of the die (GND)
6. No connection required for unlabeled bond pads

Maximum Ratings:

1.RF input power：+30dBm
2.Storage temperature: -65℃ to +150℃
3. Operating temperature: -55℃ to 125℃